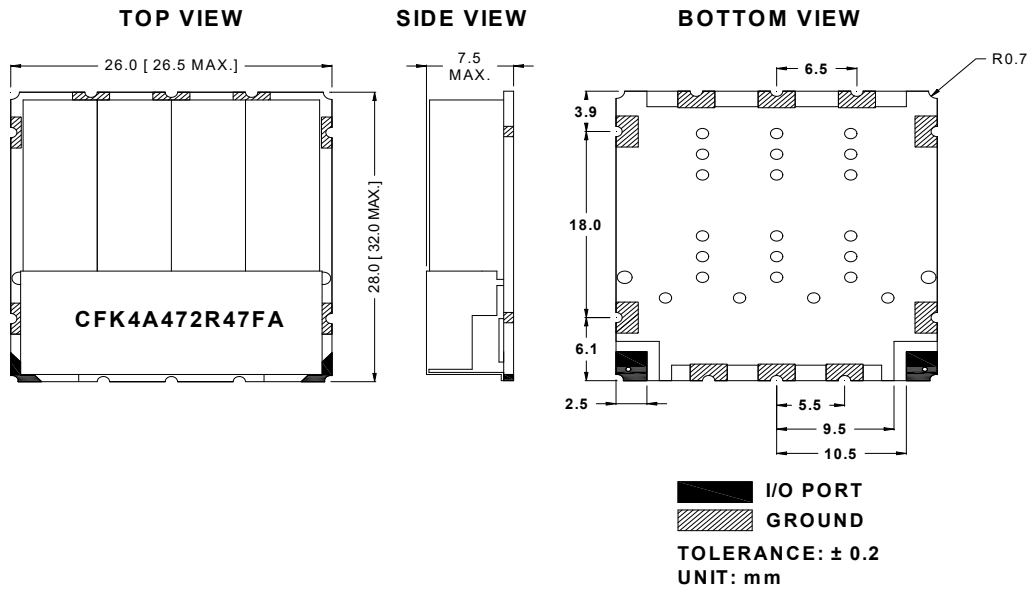


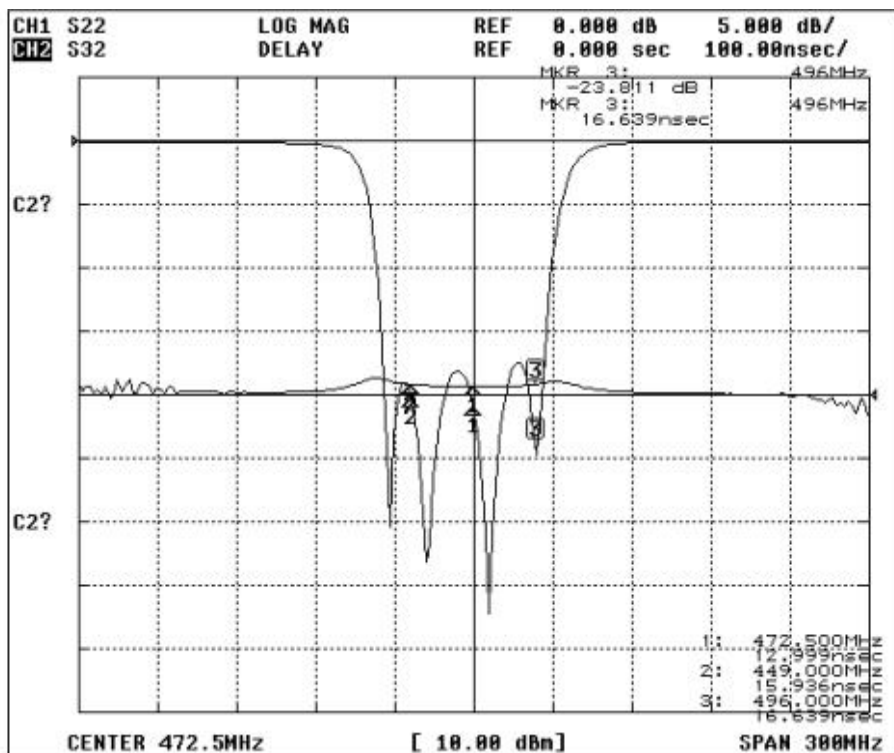
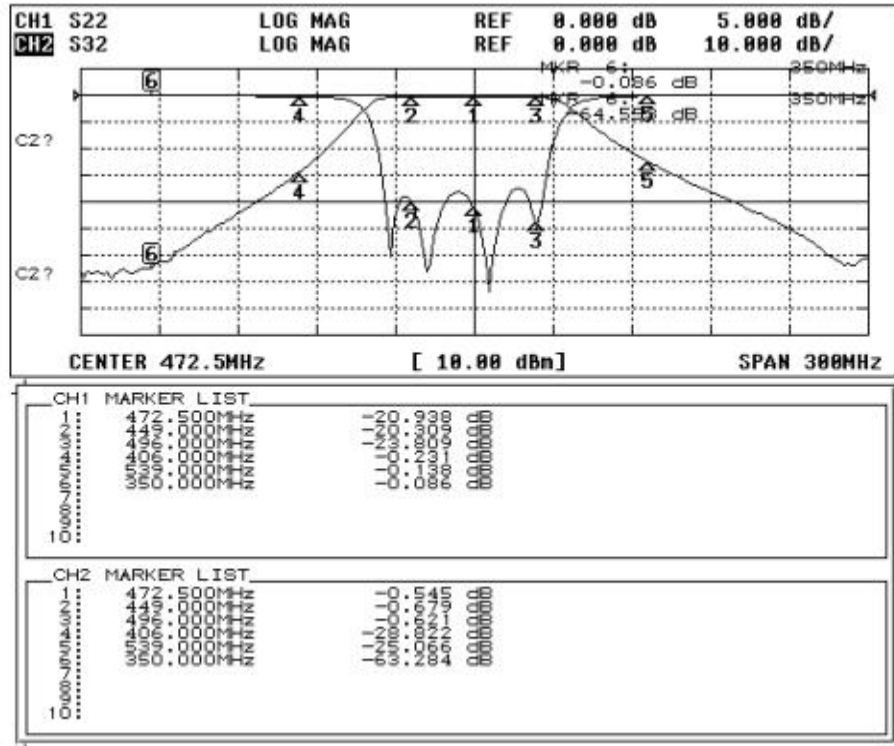
Electrical Specification

ITEMS	SPEC	UNIT
Center Frequency [fo]	472.5	MHz
Bandwidth [BW]	$f_o \pm 23.5$ [449.0 ~ 496.0]	MHz
Insertion Loss in BW	1.5	dB max
Ripple in BW	0.4	dB max
Return Loss in BW	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	20.0 dB min @ $f_o \pm$ [406.0 ~]	MHz
	20.0 dB min @ $f_o \pm$ [539.0 &]	MHz
	60.0 dB min @ $f_o \pm$ [350.0 &]	MHz
	dB min @ $f_o \pm$ [&]	MHz
Group Delay Variation	5.0	ns max
Input Power		W max.
In/Out Impedance	50 Ω	
Operation Temperature Range	-40°C to +85°C	

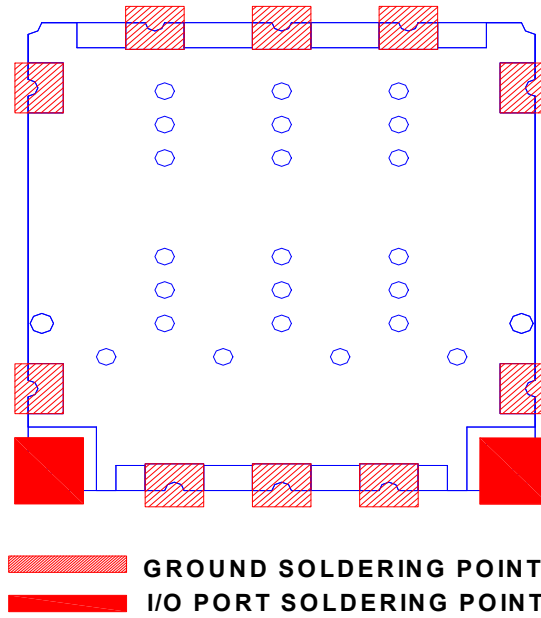
Mechanical Specification



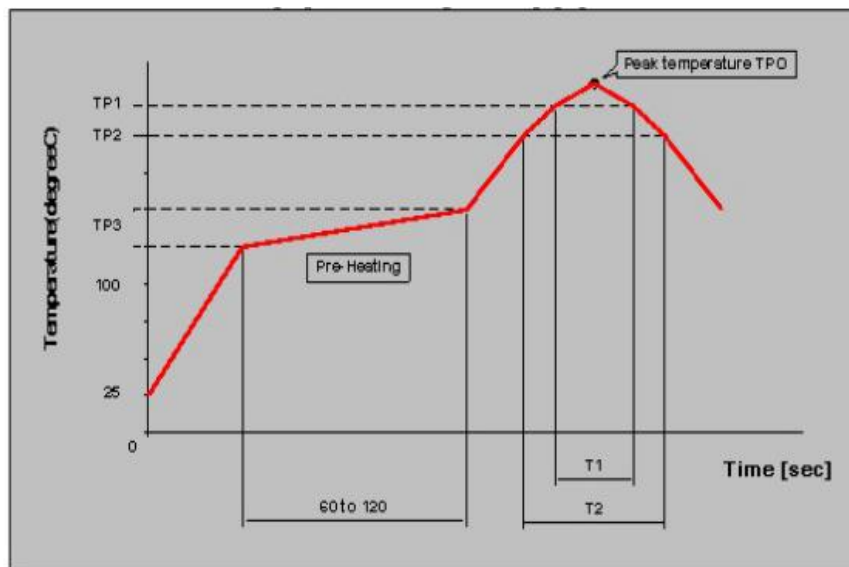
Plot Data



Recommanded PC Board Pattern



Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260±5/-0	240	20	220	70	150 to 180